

AMENDMENTS

In the Claims:

1. (Currently Amended) A test socket or adapter device adapted for carrying a semiconductor device to be tested, the test socket device comprising:

at least one connection pin, the connection pin being configured to be introduced into a corresponding recess of a contact device of a device to which the socket ~~or adapter~~ device is to be connected;

wherein at least one section of the connection pin is made of a resilient material and comprises a curved shape ~~is configured~~ such that a clamping connection is provided between the contact device and the connection pin when the at least one section of the connection pin is introduced into the recess the contact device.

2. (Currently Amended) The socket ~~or adapter~~ device according to claim 1, wherein the socket ~~or adapter~~ device is a semiconductor device testing socket ~~or semiconductor device testing adapter, respectively,~~ which is configured such that, for testing a semiconductor device, it is loaded with a corresponding semiconductor device.

3. (Currently Amended) The socket ~~or adapter~~ device according to claim 1, wherein the socket ~~or adapter~~ device is a burn-in socket ~~or a burn-in adapter, respectively,~~ which is configured such that, for performing a burn-in test, it is loaded with a corresponding semiconductor device.

4. (Canceled)

5. (Currently Amended) The socket ~~or adapter~~ device according to claim [[4]] 1, wherein the ~~metal alloy includes~~ resilient material is a metal alloy comprising copper and/or beryllium.

6. (Canceled)

7. (Currently Amended) The socket ~~or adapter~~ device according to claim [[6]] 1, wherein the at least one section of the connection pin has the shape of a wave attenuated in a direction leading away from the socket ~~or adapter~~ device.

8. (Currently Amended) The socket ~~or adapter~~ device according to claim 1, wherein the device comprising the contact device is a circuit board configured to be connected to a testing apparatus.

9. (Currently Amended) The socket ~~or adapter~~ device according to claim 1, wherein the device comprising the contact device is a testing apparatus.

10. (Canceled)

11. (Currently Amended) A system, comprising:
at least one socket ~~or adapter~~ device adapted to carry a semiconductor device to be tested; and
at least one semiconductor device testing apparatus or at least one circuit board,
wherein the socket ~~or adapter~~ device comprises at least one connection pin which is configured to be introduced into a corresponding recess of a contact device for connection to the testing apparatus or to the circuit board that can be connected with a testing apparatus, and

~~wherein at least one section of the connection pin is made of a resilient material and comprises a curved shape is configured~~ such that a clamping connection is provided between the contact device and the connection pin when the at least one section of connection pin is introduced into the recess of the contact device.

12. (Previously Presented) The system according to claim 11, wherein the connection between the connection pin and the contact device is performed without soldering.

13. (Currently Amended) The system according to claim 12, wherein the socket ~~or adapter~~ device comprises a plurality of connection pins that are connected with respectively corresponding contact devices, and wherein the connections between the connection pins and the respectively corresponding contact devices each are performed without soldering.

14. (Currently Amended) A method for testing semiconductor devices, comprising:
connecting a socket ~~or adapter~~ device to a testing system, wherein at least one connection pin of the socket ~~or adapter~~ device is introduced into a recess in a corresponding contact device; and

loading the socket ~~or adapter~~ device with a semiconductor device to be tested,
wherein at least one section of the connection pin is made of a resilient material and comprises a curved shape is configured such that a clamping connection is provided between the contact device and the connection pin when the at least one section of the connection pin is introduced into the recess of the contact device.